

### IN THE SPECIFICATION

On page 1, please delete the title in its entirety, and please substitute the following:

--SEMICONDUCTOR HAVING FILM ELECTRODES AND PROTRUDING  
ELECTRODES ON OPPOSITE SURFACES THEREOF--

Please rewrite the paragraph beginning on page 2 line 12, and ending on page 3,  
line 2, as follows:

*B1* Patent Publication No. JP3033576 JP2000-243728 discloses another process for fabricating a large number of semiconductor devices at a time. The chip-type semiconductor device obtained by the process is shown in Fig. 1, wherein a semiconductor chip 11 includes a MOSFET (not shown) having source and gate electrodes 12a and 12b on the rear surface of the chip, an insulator resin film 13 covering the rear and the side surfaces of the semiconductor chip 11 except for the tops of the electrodes 12a and 12b, and a drain electrode 14 made of conductive resin and extending from the front surface of the chip 11 to the rear surface, and an overall resin coat 23 covering the semiconductor device on the front and side surfaces thereof. The semiconductor device is mounted on a printed circuit board with the rear surface of the semiconductor device being opposed to the printed circuit board.